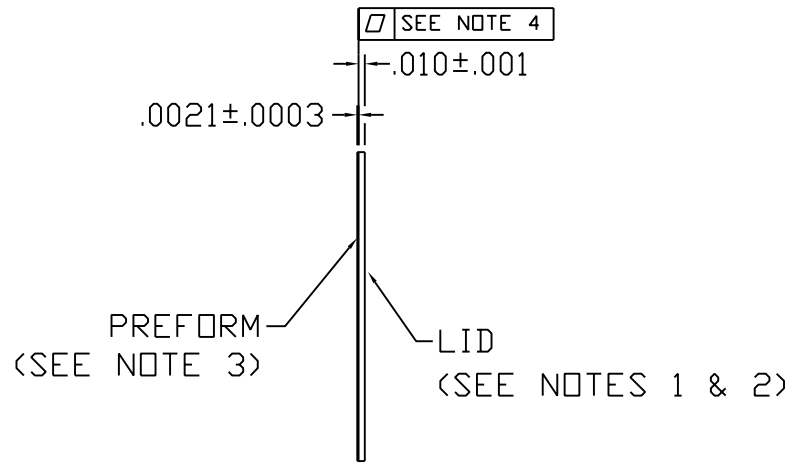
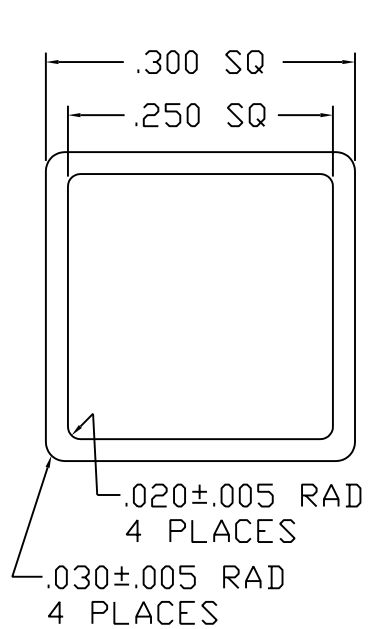


SSM P/N CL-30010



NOTES

1. MAT'L : KOVAR OR ALLOY 42
 2. PLATING : 1st LAYER 50/350 MICROINCHES Ni
2nd LAYER Au
3rd LAYER 50/350 MICROINCHES Ni
4th LAYER 25 MICROINCHES MINIMUM Au
 3. PREFORM - 80% ±1% Au
20% Sn
 4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
 5. TOLERANCES TO BE (XXX) 3 PLACES ±.002 UNLESS OTHERWISE NOTED
- NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

DESCRIPTION	
HI REL COMBO LID	
PART NO	
CL-30010	
Spectrum Semiconductor Materials, Inc. 2027 O'Toole Ave San Jose, CA 95131 PH: (408) 435-5555 Fx: (408)435-8226	MFG WILLIAMS ADVANCED MATERIALS
	MFG DRAWING NO W537H

